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Achieve 2ps/inch skew in a differential pair for 112Gbps PAM4 Design

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Virtual ▪ November 1-4, 2022



Contents

- Challenge: Skew could kill 112Gbps PAM4
- Root cause: fiber weave skew
- Mitigation methods for fiber weave skew
 - High spread-out glass fabric
 - Rotation
 - 2 ply stack-up
 - Low-dk glass fabric
- Test result with 2 ply stack-up
- Summary and Key takeaways
- Reference



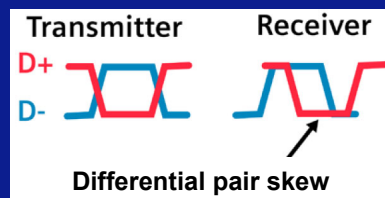
Achieve 2ps/inch skew in a differential pair for 112Gbps PAM4 Design

2022

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Challenge: Skew could kill 112Gbps PAM4

- Differential pair skew to insertion loss



$$S_{dd12} = \frac{|IL|}{2} (e^{j\theta_{13}} + e^{j\theta_{24}}) - \frac{|X|}{2} (e^{j\theta_{14}} + e^{j\theta_{23}})$$

$$|X| \ll |IL|$$

$$S_{dd12} = \frac{|IL|}{2} (e^{j\theta_{13}} + e^{j\theta_{24}})$$

$$\theta_{13} = \theta + \frac{\Delta\theta}{2}$$

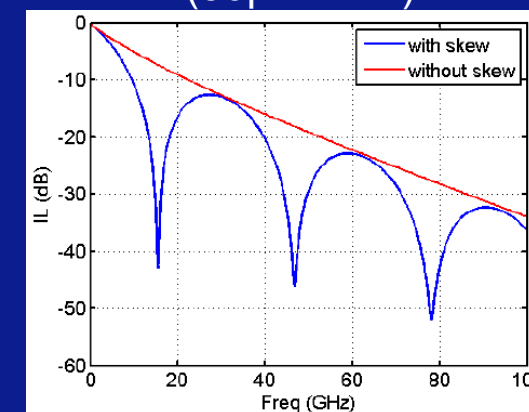
$$\theta_{24} = \theta - \frac{\Delta\theta}{2}$$

Using Euler's equation & trigonometric identities

$$S_{dd12} = |IL| \cos\left(\frac{\Delta\theta}{2}\right) e^{j\theta}$$

$\Delta\theta$ represent skew in angle

Insertion Loss (30ps skew)



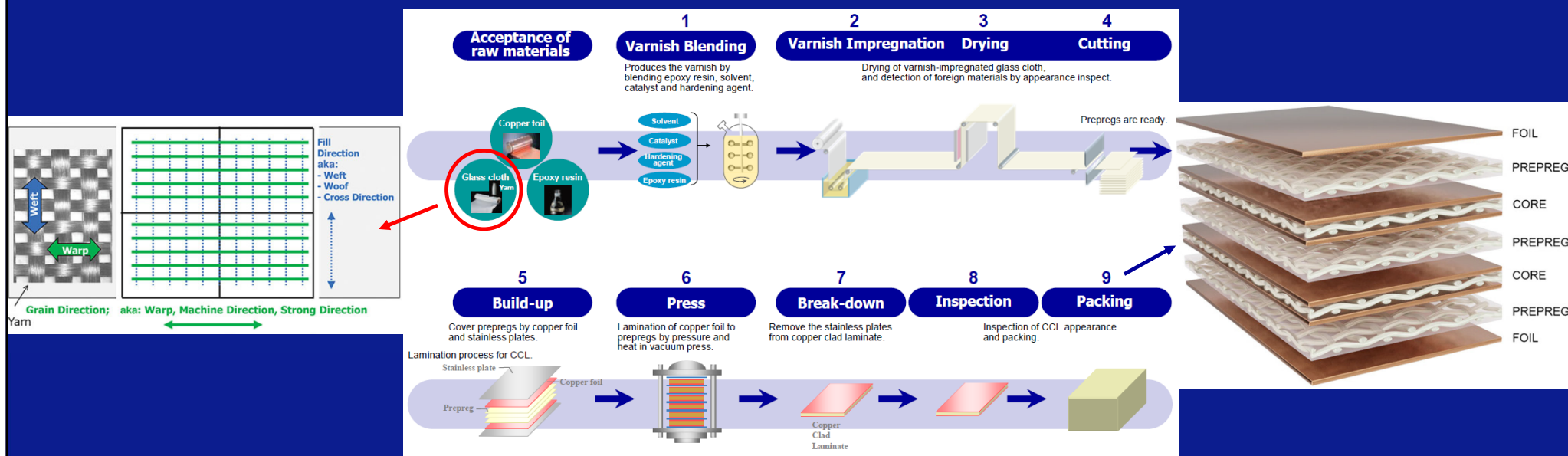
Data Source: Reference 1.

Challenge: Skew could kill 112Gbps PAM4

- ATE load-board design key request
 - 112Gbps PAM4 loopback (DUT tx → DUT rx), UI = 17.86ps
 - 2.5inch trace length to get around -10dB insertion loss
 - Diff pair skew < 10ps (experience value) ★ ★ ★
- Sources of skew
 - Asymmetries in differential signal routing (length match)
 - Fiber weave effect ★ ★ ★
 - PCB manufacturing limitations (like via stub asymmetry)

Root cause: fiber weave skew

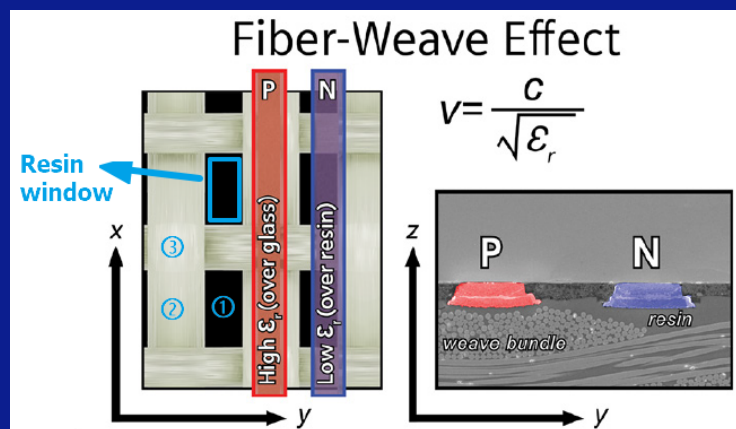
- Fiber weave in PCB material



Data Source: Reference 4.

Root cause: fiber weave skew

- Fiber weave effect



Data Source: Reference 4.

- $dk(\epsilon_r)$ of glass ~ 6
- $dk(\epsilon_r)$ of resin ~ 4
- Propagation delay could be different between P&N
- Typical diff pair skew: 10ps \sim 100ps

- Resin window example

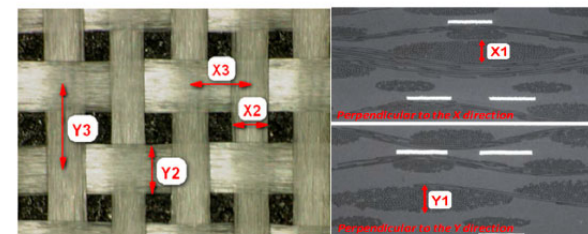


Figure 3. Photos to illustrate fiber weave bundle parameters.

Table 1. Measurement results of fiber weave bundle parameters.

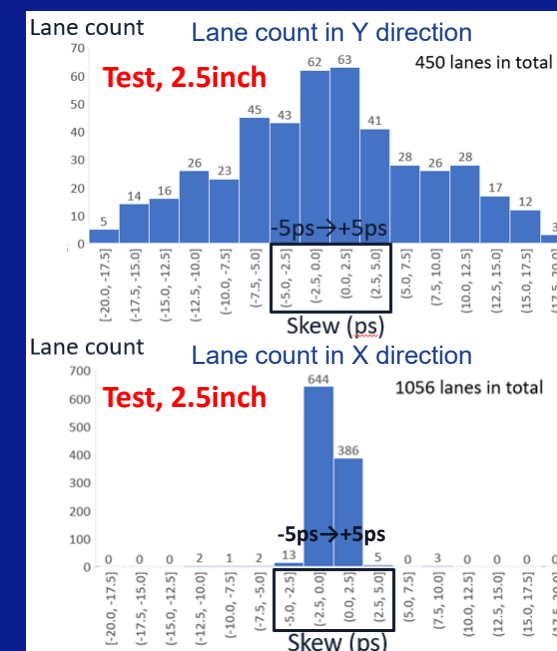
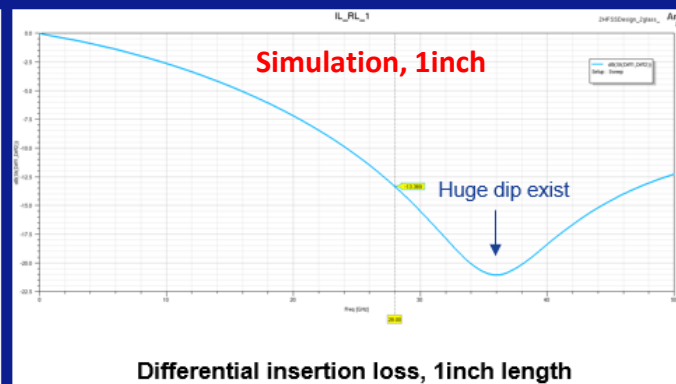
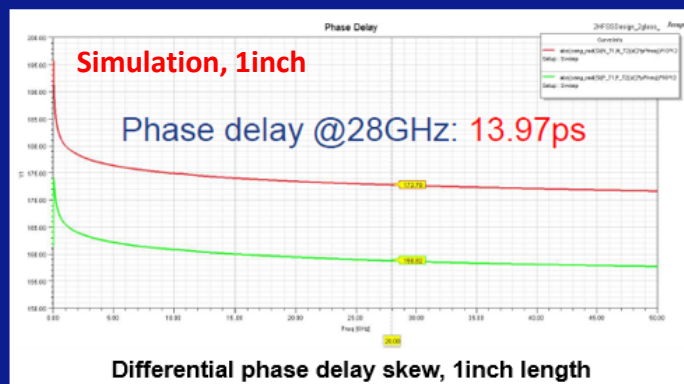
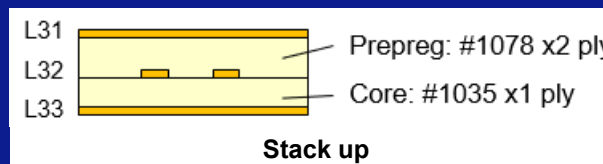
Style	Measurement Results (mil)					
	X1	X2	X3	Y1	Y2	Y3
1035	0.82	8.8	14.2	0.78	12.4	13.7
1080	1.6	8.2	17.0	1.1	12.1	22.4
1078	1.4	14.2	16.2	1.0	17.6	17.8
3313	1.9	13.1	16.2	1.5	11.0	16.3
2116	2.2	14.1	17.2	2.0	15.5	17.3

Data Source: Reference 2.

- Resin window size varies among difference glass style
- In most cases, Resin window size $X3-X2 \neq Y3-Y2$

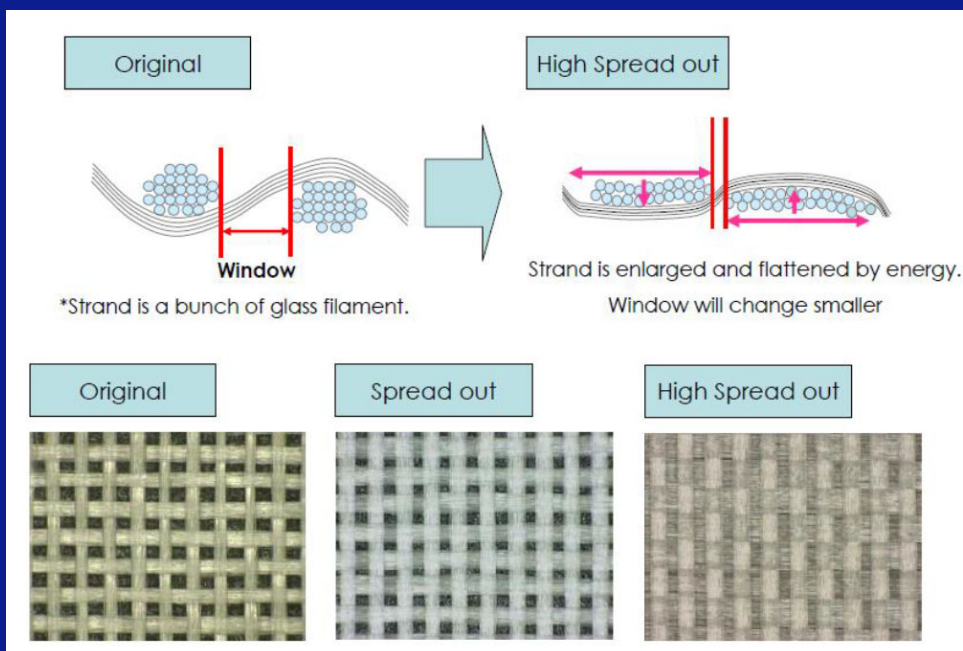
Root cause: fiber weave skew

- If fiber weave effect is not considered
 - Length matching between P&N < 1mil
 - Same via stub length
 - Traces are routed in either X direction or Y direction
 - Test will fail !!!



Mitigation methods for fiber weave skew

- Minimize Resin Windows by using **High Spread-out** glass fabric
 - Minimize dk difference inside dielectric material



We use #1035 & #1078 in the Test, already High Spread-Out type
However, still have 8ps/inch skew

MEGTRON6K E-glass

Style	Standard	Spread Out	High Spread Out
1027	No	No	Yes
1035	No	No	Yes
1078	No	No	Yes
1080	No	Yes	No
3313	No	Yes	No
2116	No	Yes	No

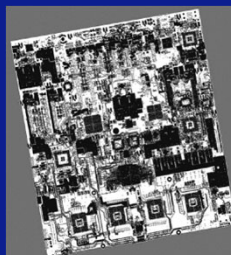
Data Source: Reference 3.

Data Source: Reference 3.

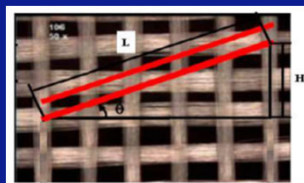
Mitigation methods for fiber weave skew

- Rotation (Gerber / CAM data / Trace)
 - Balance dk variation between P&N in a diff pair

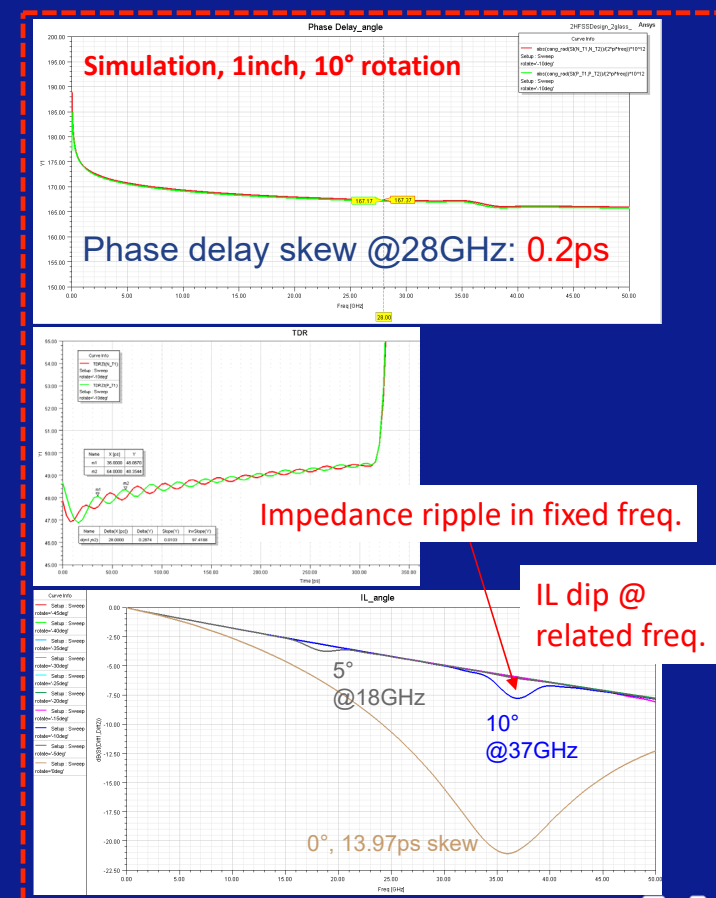
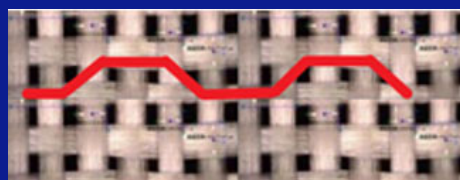
a) Gerber / CAM rotation



b) Trace rotation

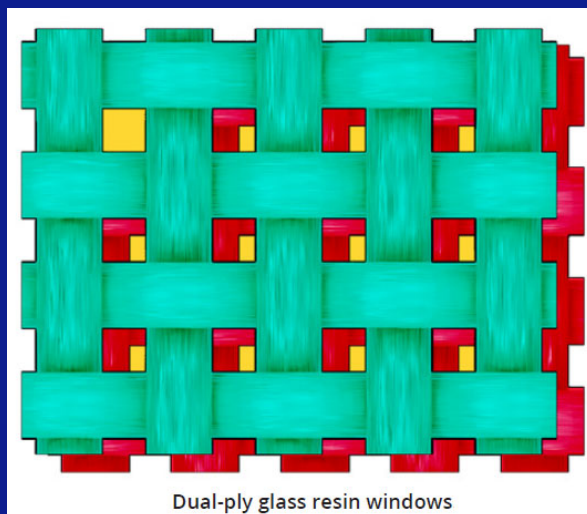
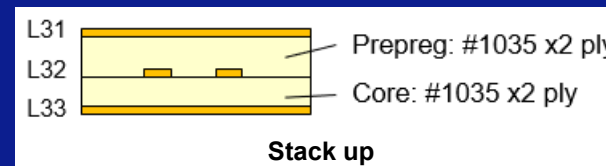


c) Zig-Zag routing

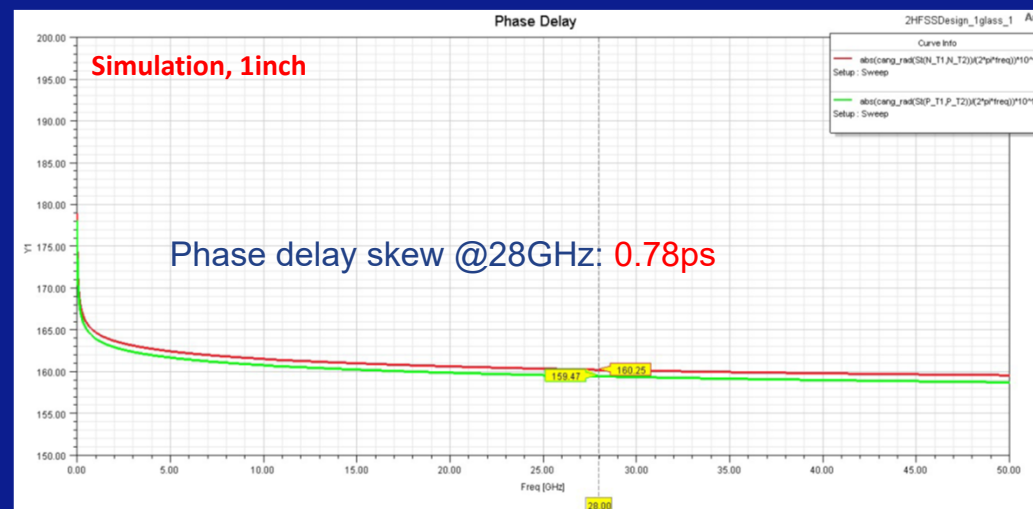


Mitigation methods for fiber weave skew

- 2 ply core + 2 ply PP stack-up
 - Minimize dk difference inside dielectric material



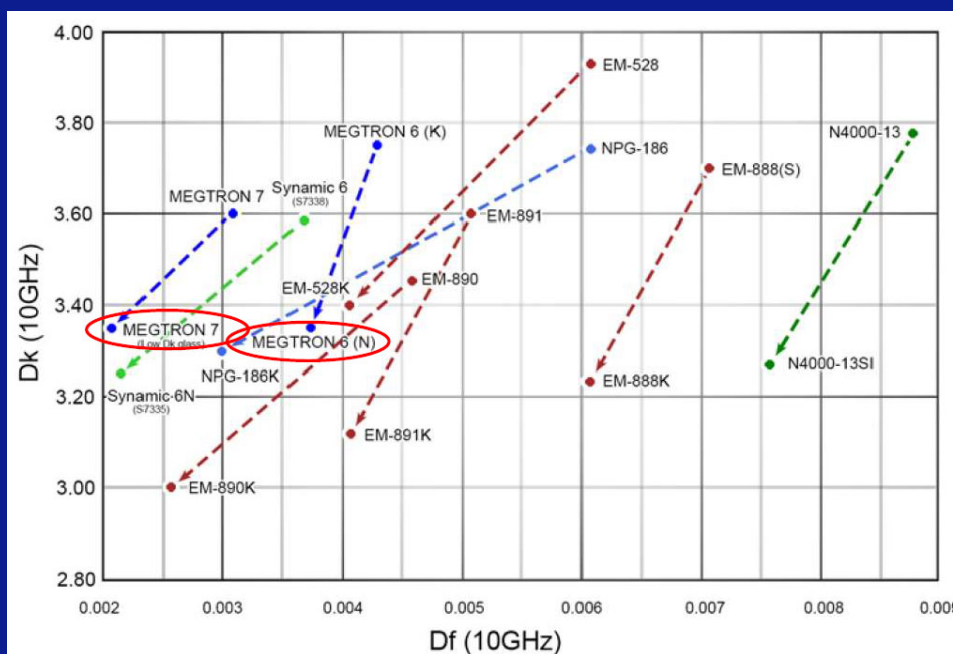
Data Source: Reference 4.



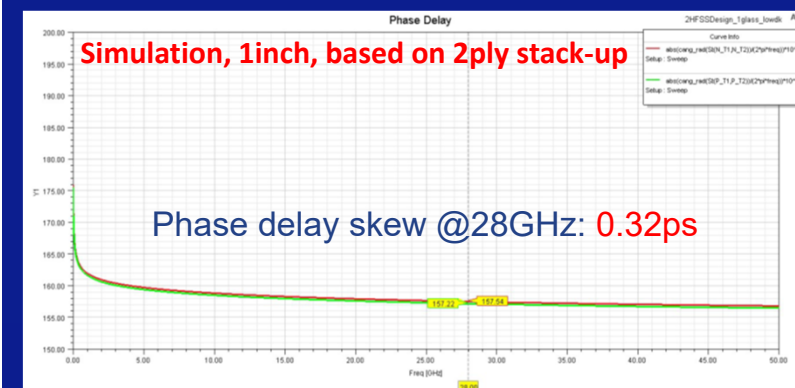
1. 2 plies of glass have little likelihood of aligning identically under one another.
2. The second ply serves to reduce the single-ply resin window size and hence glass-weave skew

Mitigation methods for fiber weave skew

- Low-dk glass fabric
 - Minimize dk difference inside dielectric material

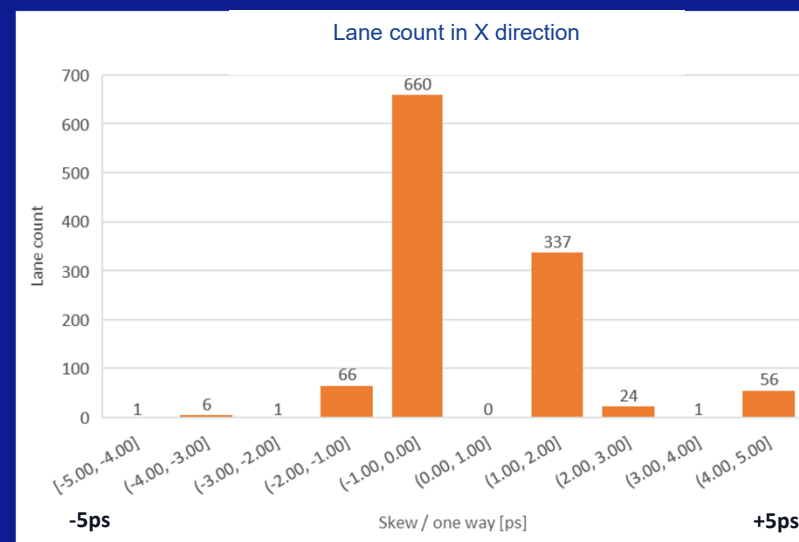
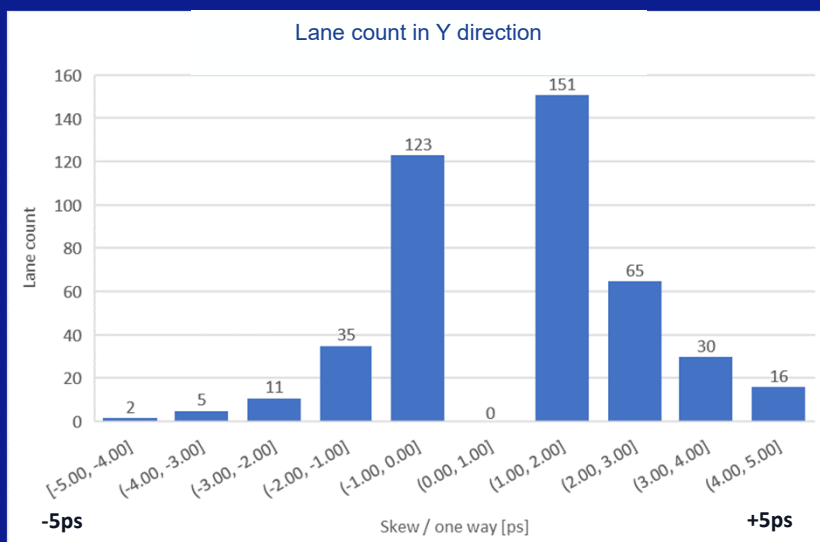
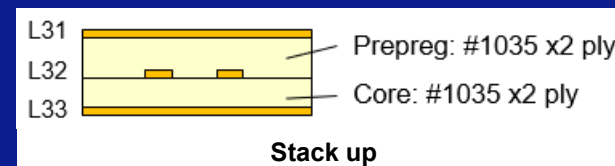


Data Source: Reference 4.



Test result with 2 ply stack-up

- Test result for reference (2.5inch length, 2 ply stack-up)



1. Achieved 2ps/inch
2. 5ps maximum < 10ps requirement
3. No issue found in loopback test !!!

Summary and Key takeaways

- Fiber weave skew occur *randomly*, prevention is much more realistic than prediction
- 4 feasible mitigation methods, *must* discuss with your fab vendor in early design stage

	Name	Phase delay skew @28GHz
1	High spread-out glass fabric	13.97ps/inch
2	Rotation	From 13.97ps/inch To 0.2ps/inch (10 degree)
3	Use 2 ply stack-up	From 13.97ps/inch To 0.78ps/inch
4	Use low-Dk glass fabric	From 13.97ps/inch To 0.32ps/inch (w/ 2 ply)

- We can combine some of those 4 methods above together to get better skew

Reference

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